

IN THE CLAIMS:

Cancel claims 2, 4, 11 through 13, and 14

Please amend the claims as follows:

1. (Currently Amended) An overlay target comprising:
a material surface;
at least ~~one~~three rectangular elongated registration features having adjacent sides of unequal length trench-in said material surface, said at least ~~one~~three rectangular elongated registration features each trench-having a bottom surface, ~~and including~~ a series of substantially vertically extending laterally continuous raised lines originating at said bottom surface of said rectangular elongated registration feature trench, substantially all of said raised lines having surfaces which are substantially coplanar with said material surface, and a series of trenches disposed between said raised lines within said rectangular elongated registration feature, said at least three rectangular elongated registration features defining a perimeter of a geometric shape.
2. (Canceled)
3. (Currently Amended) The overlay target of claim 1, wherein said at least ~~one~~three rectangular elongated registration feature trench-comprises a ~~plurality of four rectangular elongated registration features trenches~~ defining said overlay target, each of said ~~plurality of four rectangular elongated registration features trenches~~ includes said series of substantially vertically extending laterally continuous raised lines originating at said bottom surface of said registration feature trench, and said series of trenches disposed between said raised lines within said rectangular elongated registration feature, said four rectangular elongated registration features defining a continuous perimeter of a rectangle.

4. (Canceled)

5. (Currently Amended) An overlay target comprising:
a material surface;
at least one generally square registration feature ~~pad-area~~ in said material surface, said at least one generally square registration feature ~~pad-area~~ having a bottom surface, and including a series of substantially vertically extending laterally continuous raised lines extending in a parallel manner across said registration feature, and originating at said bottom surface of said registration feature~~pad-area~~, substantially all of said raised lines having surfaces which are substantially coplanar with said material surface, said raised lines being of equal size and dimensions, and a series of trenches disposed between said raised lines within said generally square registration feature, said trenches being of equal width and length.

6. (Currently Amended) The overlay target of claim 5, wherein said at least one generally square registration feature ~~pad-area~~ includes a plurality of generally square registration features ~~pad-areas~~ defining said overlay target, each of said plurality of generally square registration features ~~pad-areas~~ includes said series of substantially vertically extending laterally continuous raised lines originating at said bottom surface of said registration feature~~pad-area~~, and said series of trenches disposed between said raised lines within said generally square registration feature.

7. (Currently Amended) The overlay target of claim 6, further comprising at least one rectangular elongated registration feature ~~trench~~ including said series of substantially vertically extending laterally continuous raised lines originating at a bottom surface of said rectangular elongated registration feature~~overlay target~~.

8. (Currently Amended) A semiconductor wafer comprising:
a semiconductor substrate having a material surface; and

an overlay target in said material surface, having at least three rectangular elongated registration features having adjacent sides of unequal length, said at least three rectangular elongated registration features each having a bottom surface comprising at least one series of substantially vertically extending laterally continuous raised lines originating at said bottom surface of said rectangular elongated registration feature~~overlay target~~, substantially all of said raised lines having surfaces which are coplanar with said material surface, and a series of trenches disposed between said raised lines within said rectangular elongated registration feature, said at least three rectangular elongated registration features defining a perimeter of a geometric shape.

9. (Currently Amended) The semiconductor wafer of claim 8, wherein said at least one series of substantially vertically extending laterally continuous raised lines is etched into said semiconductor substrate.

10. (Currently Amended) The semiconductor wafer of claim 8, wherein said at least one series of substantially vertically extending laterally continuous raised lines is etched into a material layer overlying said semiconductor substrate.

11. (Cancelled)

12. (Cancelled)

13. (Cancelled)

14. (Cancelled)

15. (Currently Amended) The semiconductor wafer of claim 8, wherein said at least one series of substantially vertically extending laterally continuous raised lines comprises a first

series of raised lines disposed in a rectangular elongated registration feature pad area, said overlay target further comprising and a second series of raised lines disposed in a generally square registration feature trench.